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AN - 2003-674043 [64]
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AP - JP20010299805 20010928

**CPY - TOPP** 

DC - A85 L03 P73 U14 V04

FS - CPI:GMPI:EPI

IC - B32B15/08; C08J5/18; C08K3/00; C08L101/00; H05K1/16; H05K3/46

MC - A08-M09A A08-R01 A09-A03 A12-E07A L03-H04E1 L03-H04E3

- U14-H04A3 V04-Q04 V04-R05A V04-R07P1

PA - (TOPP) TOPPAN PRINTING CO LTD

PN - JP2003105205 A 20030409 DW200364 C08L101/00 006pp

PR - JP20010299805 20010928

XA - C2003-184409

XIC - B32B-015/08; C08J-005/18; C08K-003/00; C08L-101/00; H05K-001/16; H05K-003/46

XP - N2003-538099

- AB JP2003105205 NOVELTY The high-dielectric-constant composite material has thermosetting resin such as epoxy resin, 10-50 mass% of thermoplastic resin with respect to total resin solid content, and dielectric filler.
  - DETAILED DESCRIPTION INDEPENDENT CLAIMS are also included for the following:
  - (1) high-dielectric-constant film;
  - (2) laminated plate with metallic foil; and
  - (3) printed wiring board.
  - USE For dielectric-constant film (claimed) of printed wiring board for electronic device.
  - ADVANTAGE Possess excellent dielectric characteristics and does not produce crack even due to influence of temperature.
  - DESCRIPTION OF DRAWING(S) The figure shows the manufacturing process of a printed wiring board.
  - copper foil 1,7
  - insulating layer 2,3,5,6
  - high dielectric constant film 4
  - (Dwg.1/2)
- IW HIGH DIELECTRIC CONSTANT COMPOSITE MATERIAL PRINT WIRE BOARD ELECTRONIC DEVICE PREDETERMINED AMOUNT THERMOSETTING RESIN THERMOPLASTIC RESIN DIELECTRIC FILL
- IKW HIGH DIELECTRIC CONSTANT COMPOSITE MATERIAL PRINT WIRE BOARD ELECTRONIC DEVICE PREDETERMINED AMOUNT THERMOSETTING RESIN THERMOPLASTIC RESIN DIELECTRIC FILL

NC - 001

OPD - 2001-09-28

ORD - 2003-04-09

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- TI High-dielectric-constant composite material for printed wiring board in electronic device, has predetermined amount of thermosetting resin, thermoplastic resin and dielectric filler
- A01 [001] 018; P0464-R D01 D22 D42 F47; S9999 S1434; H0328
  - [002] 018; P0986 P0964 H0293 F34 D01 D11 D10 D18 F26; H0317; S9999 S1434
  - [003] 018; P1047 P0964 P1490 H0260 F34 F61 D01; H0260; S9999 S1434: H0317
  - [004] 018 : P1081-R F72 D01 : P0077 : H0317 : S9999 S1434
  - [005] 018; ND01; ND04; Q9999 Q7454 Q7330; Q9999 Q7374-R Q7330;
    B9999 B3214 B3203 B3190; K9745-R; N9999 N7192 N7023; Q9999
    Q7818-R; K9552 K9483; K9574 K9483; B9999 B3849-R B3838 B3747
  - [006] 018; A999 A135; A999 A237; B9999 B3203-R B3190